

JOINING MATERIAL, PRODUCTION METHOD FOR JOINING MATERIAL, AND
JOINED BODY

[ABSTRACT]

In the joined body (10) in which the conductor (12) and the substrate (14) are
5 joined by the joining material (13), the joining material (13) includes a sintered body
formed by sintering silver powder. A sintered body having a porosity of 8% to 30% and
a surface roughness Ra of a joining surface of 500 nm or more and 3.3 μm or less is
adopted.

[Fig. 1]